



Final Product Change Notification

201909001F01

Issue Date: 24-Dec-2019

Effective Date: 24-Jan-2020

Here's your personalized quality information concerning products Digi-Key purchased from NXP.

For detailed information we invite you to view this notification online

This notice is NXP Company Proprietary.



QUALITY

Management Summary

SOT886 assembly and test will be transferred from ATGD and ATSN to ATBK. This streamlines manufacturing flow and improves package reliability with introduction of roughened leadframe and Cu wire.

Change Category

- | | | | | |
|--|--|---|--|---|
| <input type="checkbox"/> Wafer Fab Process | <input checked="" type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input checked="" type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input checked="" type="checkbox"/> Assembly Location | <input checked="" type="checkbox"/> Packing/Shipping/Labeling | <input checked="" type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

XSON6 (SOT886) Assembly/Test Transfer from ATGD and ATSN to ATBK

Description of Change

NXP Semiconductors is transferring assembly and test of the SOT886 (XSON6) package from ATSN and ATGD to ATBK. Standard ATBK BOM and flows will be used.

Product data sheets are updated and available on the NXP website indicating the new orderable part numbers reflecting the use of Static Shielding Bags (SSB).

Reason for Change

Move production to an NXP facility to assure product quality and delivery.

Identification of Affected Products

Packing Labels will show Product Manufacturing Code (PMC) "n" to reflect ATBK assembly.

Product Availability

Sample Information

Samples are available upon request

Production

Shipment dates are product specific, see attached plan

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
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201909001A	16-Sep-2019		XSON6 (SOT886) Assembly/Test Transfer from ATGD and ATSN to ATBK
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Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 23-Jan-2020.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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NXP Semiconductors

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Affected Part Numbers

NCX2200GM,115

NX3L1T3157GM,115